

## **LISTING OF CLAIMS**

The following listing of claims indicates the current status of all claims in the present application.

21. (Previously presented) A semiconductor device comprising:
- a semiconductor chip;
  - a bump disposed on a surface of the semiconductor chip;
  - a protective member disposed on the surface of the semiconductor chip, the protective member having an opening portion from which the bump is exposed; and
  - a movable portion disposed on a region that is covered by the protective member.
22. (Previously presented) The semiconductor device according to claim 21, wherein the movable portion has a movable electrode detecting change of a capacity.
23. (Previously presented) The semiconductor device according to claim 21, wherein the movable portion provides a capacity detection type acceleration sensor.
24. (Previously presented) The semiconductor device according to claim 21, wherein the movable portion faces the protective member.
25. (Previously presented) The semiconductor device according to claim 24, wherein the protective member is formed to provide a space for preventing contact with the movable portion.

26. (Previously presented) The semiconductor device according to claim 25, wherein the protective member has a recess corresponding to the movable portion.

27. (Previously presented) The semiconductor device according to claim 24, wherein the movable portion is disposed in an opening portion formed on the semiconductor chip.

28. (Previously presented) The semiconductor device according to claim 27, wherein the opening portion includes a back surface processed portion and an adhesive film disposed on the semiconductor chip so as to cover an opening defined by the back surface processed portion.

29. (Previously presented) The semiconductor device according to claim 21, wherein the movable portion is disposed in the semiconductor chip close to the surface where the protective member is disposed.

30. (Previously presented) The semiconductor device according to claim 21, further comprising a second bump, wherein both bumps are arranged on both sides of the surface of the semiconductor chip with respect to the movable portion.

31. (Previously Presented) A semiconductor device comprising:

a semiconductor chip having first and second plane surfaces and diced outer surfaces, the semiconductor chip defining an opening portion that opens to the first plane surface, the semiconductor chip having a movable portion disposed in the opening portion;

a pad portion formed on the first plane surface and including a bump thereon; and

a protective member disposed on the first surface so as to cover the opening portion and to expose the pad portion.

32. (Cancelled).

33. (Previously presented) The semiconductor device according to claim 31, wherein the movable portion provides a capacity detection type acceleration sensor.

34. (Previously presented) The semiconductor device according to claim 31, wherein the protective member is formed to provide a space for preventing contact with the movable portion.

35. (Previously presented) The semiconductor device according to claim 31, wherein the protective member has a cap portion.

36. (Previously presented) The semiconductor device according to claim 31, wherein the protective member has a recess corresponding to the movable portion.

37. (Previously presented) The semiconductor device according to claim 31, wherein the opening portion includes a back surface processed portion that opens to the second plane surface of the semiconductor chip, and further comprising an adhesive film disposed on the second plane surface of the semiconductor chip so as to cover an opening defined by the back surface processed portion.

38. (Previously presented) The semiconductor device according to claim 31, wherein the movable portion is disposed in the semiconductor chip close to the first plane surface.

39. (Previously presented) The semiconductor device according to claim 31, wherein the first plane surface on which the pad portion is formed is different than the opening portion in which the movable portion is disposed.

40. (Previously presented) The semiconductor device according to claim 21, wherein the bump is further disposed on another region different than the region of the movable portion.